

REMARKS

In view of the above amendments and following remarks, reconsideration and further examination are requested.

By the current amendment claim 1 has been amended.

Claims 1-6 were rejected under 35 U.S.C. 102(b) as being anticipated by Gilleo et al. and claim 7 was rejected under 35 U.S.C. 103(a) as being unpatentable over Gilleo et al. in view of Haas et al. The references relied upon by the Examiner are not applicable with regard to the currently amended claims for the following reasons.

Claim 1 has been amended to recite:

An electronic circuit device comprising:
an electronic component having a connection terminal on one side thereof;
a circuit board having an electrode pad thereon;
an adhesive sheet having a through-hole, **with a cross-sectional area of said electrode pad being greater than a cross-sectional area of said through-hole**; and
a conductive adhesive provided in said through-hole;
wherein said electronic component and said circuit board are bonded to each other via said adhesive sheet, and said connection terminal on said electronic component and said electrode pad on said circuit board are bonded to each other by said conductive adhesive in said through-hole (emphasis added).

Figures 1-4B show electrode pad 12 having a cross-sectional area that is greater than a cross-sectional area of through-hole 14.

Because the electrode pad is larger in cross-sectional area than the through-hole of the adhesive sheet formed on the circuit board, and because the connecting terminal of the electronic component and the electrode pad are coupled by a conductive adhesive, only precise displacement of the connecting terminal relative to the through-hole is required to assemble the electronic circuit device. Also, the electrode pad having a larger cross-sectional area than that of the through-hole allows for corresponding dimensions of the connecting terminal and electrode

pad to be constant even when a position of the connecting terminal changes within through-hole, and as a result, fluctuation and increase of a connecting resistance is prevented.

To the contrary, Gilleo et al. does not teach or suggest electrode pad of a circuit board having a larger cross-sectional area than that of a through-hole of an adhesive sheet. In this regard, Gilleo et al. shows that chip contact 150 and bond pad 200 are both positioned within aperture 180 of sheet 170. Thus, a cross-sectional area of bond pad 200 is not greater than that of aperture 180, and accordingly, in order to assemble the semiconductor chip package assembly of Gilleo et al., chip contact 150, bond pad 200 and aperture 180 each require precise positioning relative to one another, which leads to low productivity. Additionally, in a case where a corresponding position of chip contact 150 and bond pad 200 within aperture 180 deviate relative to one another, or when their shapes are not identical, connecting resistance of the circuit board will fluctuate and an increase in resistance will consequently result, since the resistance is dependent on a corresponding area between the chip contact and bond pad. Thus, the electronic circuit device as claimed is advantageous relative to the semiconductor chip package assembly of Gilleo et al.

Because the electronic circuit device as recited in claim 1 is not taught or suggested by Gilleo et al., claim 1 is not anticipated by Gilleo et al. Haas et al. does not resolve the above deficiencies of Gilleo et al., and accordingly, claim 1 is also not obvious over a combination of Gilleo et al. and Haas et al. Thus, claims 1-7 are allowable.

In view of the above amendments and remarks, it is respectfully submitted that the present application is in condition for allowance and an early Notice of Allowance is earnestly solicited.

If after reviewing this Amendment, the Examiner believes that any issues remain which must be resolved before the application can be passed to issue, the Examiner is invited to contact the Applicants' undersigned representative by telephone to resolve such issues.

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Respectfully submitted,

Norihito TSUKAHARA et al.

By: 

Joseph M. Gorski
Registration No. 46,500
Attorney for Applicants

JMG/nka
Washington, D.C. 20006-1021
Telephone (202) 721-8200
Facsimile (202) 721-8250
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